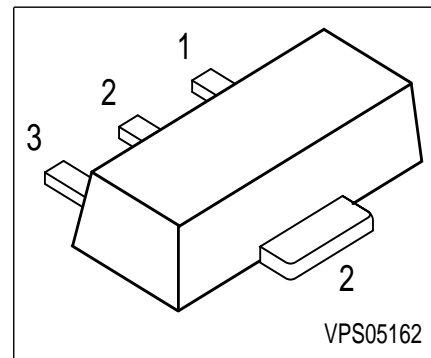


**NPN Silicon Darlington Transistors**

- For general AF applications
- High collector current
- High current gain
- Complementary types: BCV28, BCV48 (PNP)



Type	Marking	Pin Configuration				Package
BCV29	EF	1 = B	2 = C	3 = E	4 = C	SOT89
BCV49	EG	1 = B	2 = C	3 = E	4 = C	SOT89

**Maximum Ratings**

Parameter	Symbol	BCV29	BCV49	Unit
Collector-emitter voltage	$V_{CEO}$	30	60	V
Collector-base voltage	$V_{CBO}$	40	80	
Emitter-base voltage	$V_{EBO}$	10	10	
DC collector current	$I_C$	500		mA
Peak collector current	$I_{CM}$	800		
Base current	$I_B$	100		
Peak base current	$I_{BM}$	200		
Total power dissipation, $T_S = 130\text{ °C}$	$P_{tot}$	1		W
Junction temperature	$T_j$	150		°C
Storage temperature	$T_{stg}$	-65 ... 150		

**Thermal Resistance**

Junction - soldering point <sup>1)</sup>	$R_{thJS}$	≤20	K/W
------------------------------------------	------------	-----	-----

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 10\text{ mA}$ , $I_B = 0$	$V_{(BR)CEO}$				V
BCV29		30	-	-	
BCV49		60	-	-	
Collector-base breakdown voltage $I_C = 100\ \mu\text{A}$ , $I_B = 0$	$V_{(BR)CBO}$				
BCV29		40	-	-	
BCV49		80	-	-	
Emitter-base breakdown voltage $I_E = 10\ \mu\text{A}$ , $I_C = 0$	$V_{(BR)EBO}$	10	-	-	
Collector cutoff current $V_{CB} = 30\text{ V}$ , $I_E = 0$	$I_{CBO}$				nA
BCV29		-	-	100	
$V_{CB} = 60\text{ V}$ , $I_E = 0$	BCV49			100	
Collector cutoff current $V_{CB} = 30\text{ V}$ , $I_E = 0$ , $T_A = 150^\circ\text{C}$	$I_{CBO}$				$\mu\text{A}$
BCV29		-	-	10	
$V_{CB} = 60\text{ V}$ , $I_E = 0$ , $T_A = 150^\circ\text{C}$	BCV49			10	
Emitter cutoff current $V_{EB} = 4\text{ V}$ , $I_C = 0$	$I_{EBO}$	-	-	100	nA
DC current gain 1) $I_C = 100\ \mu\text{A}$ , $V_{CE} = 1\text{ V}$	$h_{FE}$				-
BCV29		4000	-	-	
BCV49		2000	-	-	
DC current gain 1) $I_C = 10\text{ mA}$ , $V_{CE} = 5\text{ V}$	$h_{FE}$				
BCV29		10000	-	-	
BCV49		4000	-	-	
DC current gain 1) $I_C = 100\text{ mA}$ , $V_{CE} = 5\text{ V}$	$h_{FE}$				
BCV29		20000	-	-	
BCV49		10000	-	-	
DC current gain 1) $I_C = 0.5\text{ A}$ , $V_{CE} = 5\text{ V}$	$h_{FE}$				
BCV29		4000	-	-	
BCV49		2000	-	-	

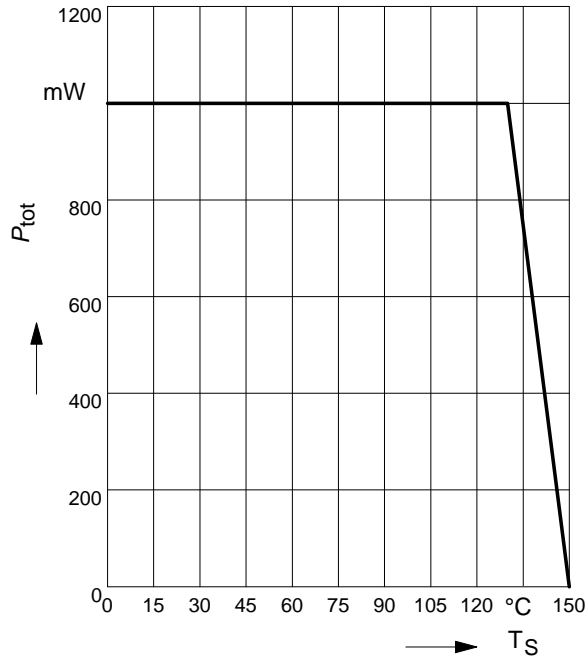
1) Pulse test:  $t \leq 300\ \mu\text{s}$ ,  $D = 2\%$

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 100\text{ mA}, I_B = 0.1\text{ mA}$	$V_{CEsat}$	-	-	1	V
Base-emitter saturation voltage 1) $I_C = 100\text{ mA}, I_B = 0.1\text{ mA}$	$V_{BEsat}$	-	-	1.5	
<b>AC Characteristics</b>					
Transition frequency $I_C = 50\text{ mA}, V_{CE} = 5\text{ V}, f = 100\text{ MHz}$	$f_T$	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10\text{ V}, f = 1\text{ MHz}$	$C_{cb}$	-	3.5	-	pF

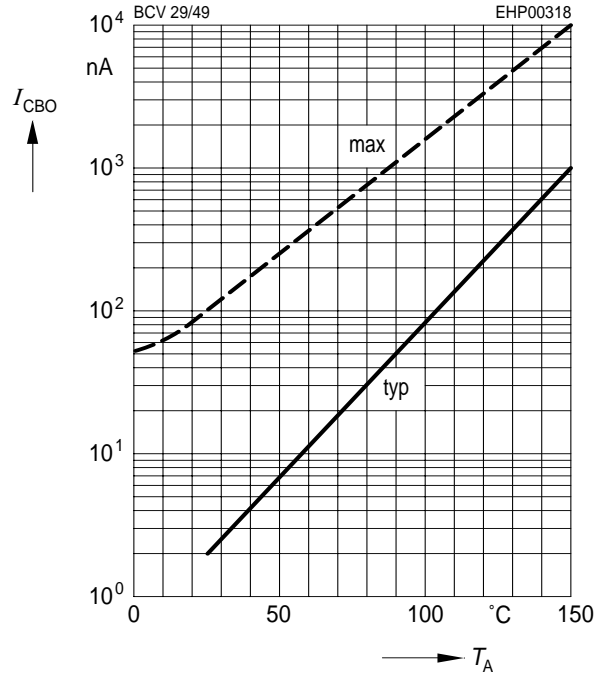
1) Pulse test:  $t \leq 300\mu\text{s}$ ,  $D = 2\%$

**Total power dissipation  $P_{tot} = f(T_S)$**



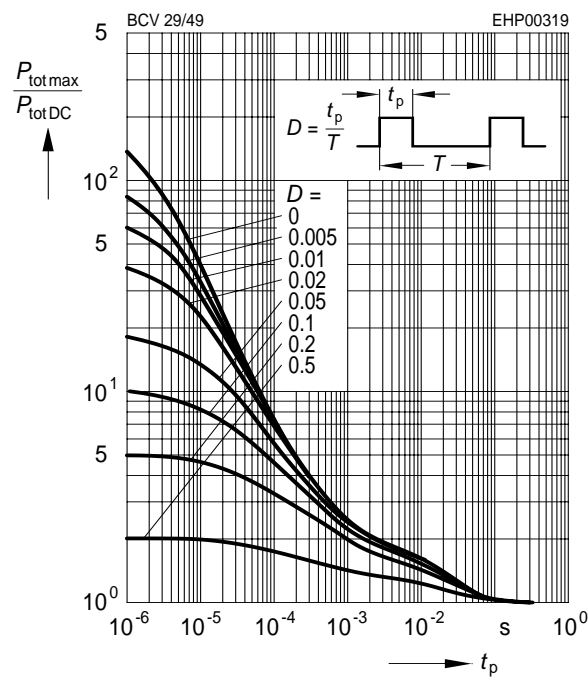
**Collector cutoff current  $I_{CBO} = f(T_A)$**

$V_{CB} = V_{CEmax}$



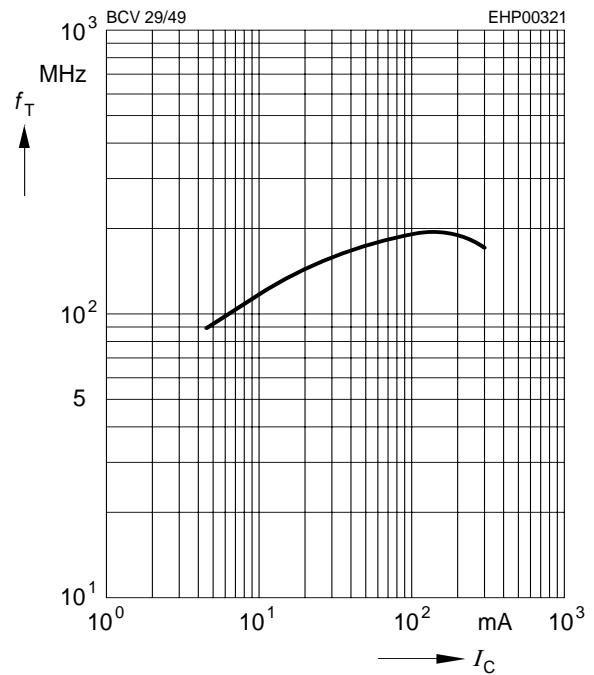
**Permissible pulse load**

$P_{totmax} / P_{totDC} = f(t_p)$



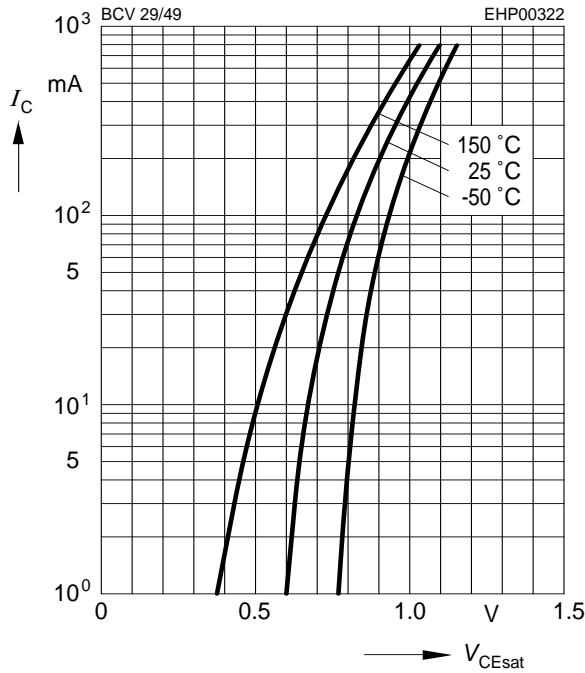
**Transition frequency  $f_T = f(I_C)$**

$V_{CE} = 5V$



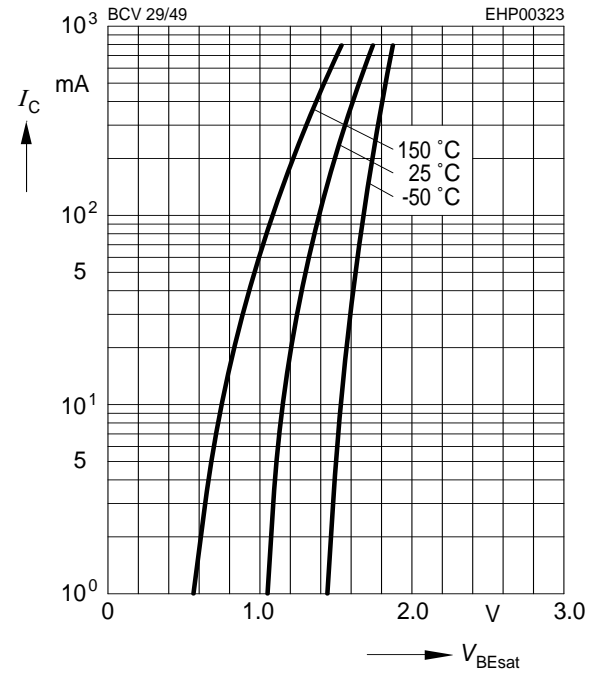
**Collector-emitter saturation voltage**

$I_C = f(V_{CEsat}), h_{FE} = 1000$

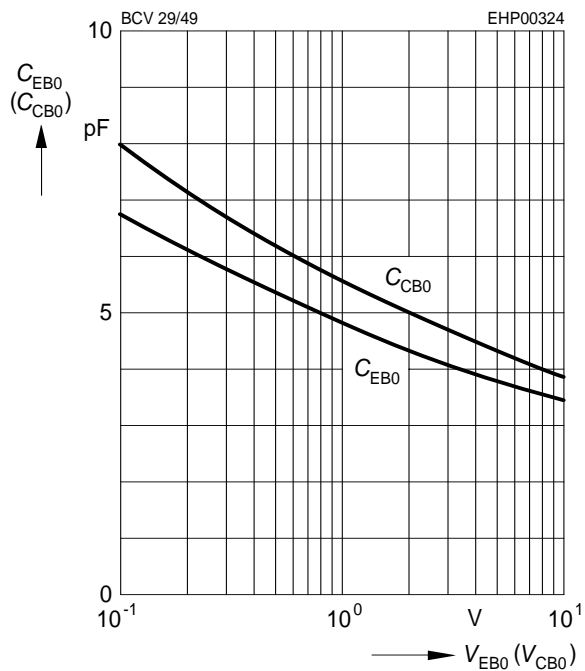


**Base-emitter saturation voltage**

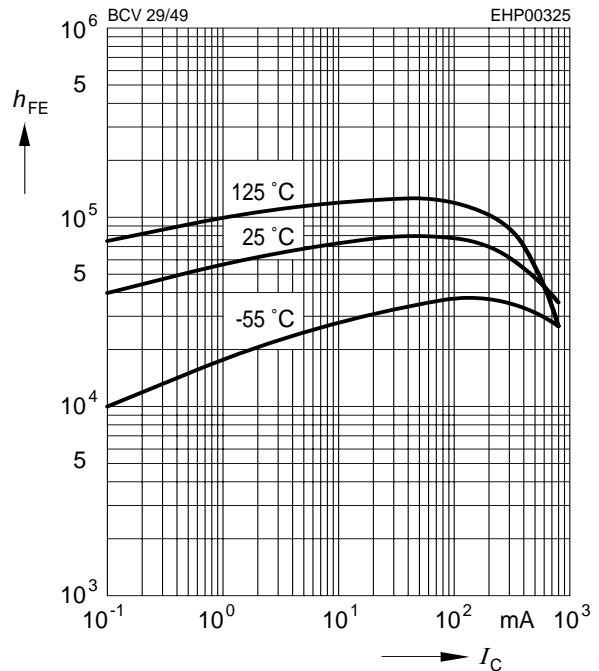
$I_C = f(V_{BEsat}), h_{FE} = 1000$



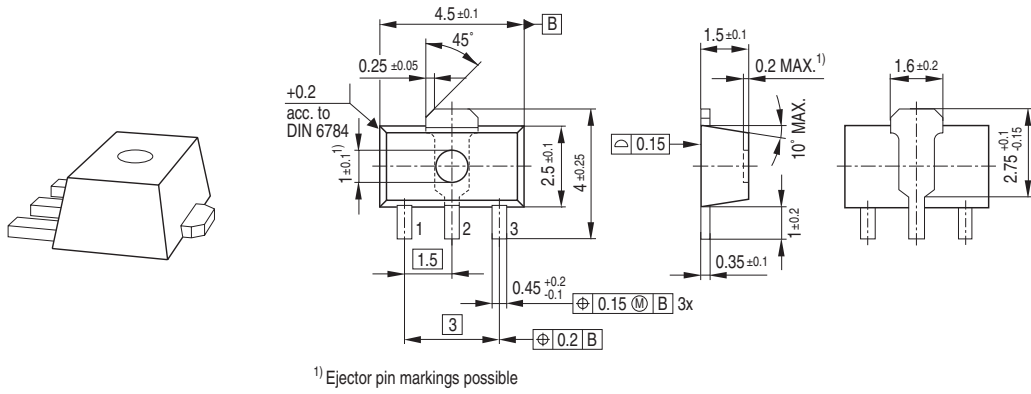
**Collector-base capacitance  $C_{CB} = f(V_{CB0})$   
Emitter-base capacitance  $C_{EB} = f(V_{EB0})$**



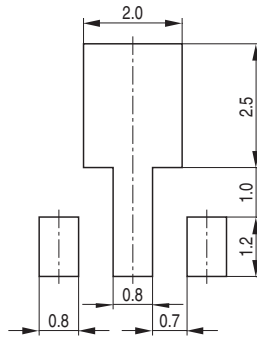
**DC current gain  $h_{FE} = f(I_C)$   
 $V_{CE} = 5V$**



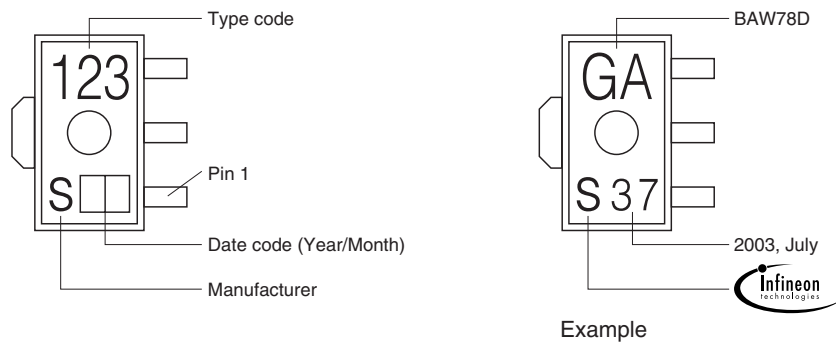
### Package Outline



### Foot Print



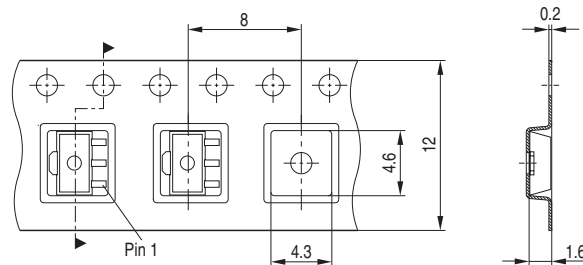
### Marking Layout



### Packing

Code E6327: Reel  $\varnothing$ 180 mm = 1.000 Pieces/Reel

Code E6433: Reel  $\varnothing$ 330 mm = 4.000 Pieces/Reel



Published by Infineon Technologies AG,  
St.-Martin-Strasse 53,  
81669 München  
© Infineon Technologies AG 2005.  
All Rights Reserved.

### **Attention please!**

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.  
Terms of delivery and rights to technical change reserved.  
We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

### **Information**

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office ([www.infineon.com](http://www.infineon.com)).

### **Warnings**

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.  
Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.